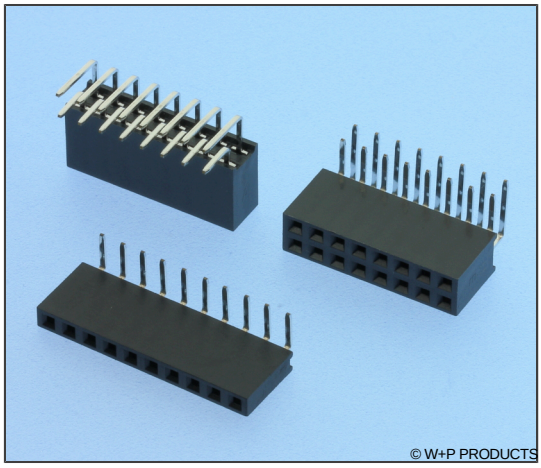
159

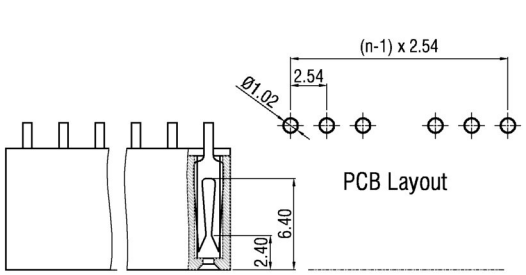
Buchsenleisten RM 2,54mm, gewinkelt, 1-/2-reihig
Female Headers, 2.54mm Pitch, Right-Angled, Single/Double Row

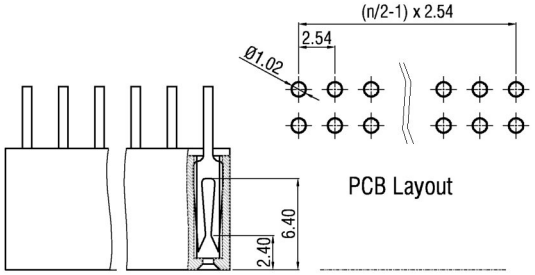
Technische Daten / ***Technical Data***

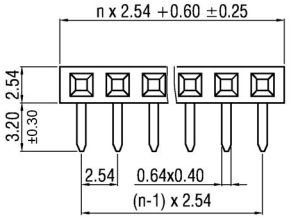
Isolierkörper	Thermoplast, nach UL94 V-0
Insulator	*Thermoplastic, rated UL94 V-0*
Kontaktmaterial	Kupferlegierung
Contact Material	*Copper alloy*
Kontaktoberfläche	Lt. Oberflächenoptionen, über Ni (1,3 ... 2,5µm)
Contact Surface	*Acc. to options (see below), over Ni (1.3 ... 2.5µm)*
RoHS-Ausnahmen 6a-I / 6c	keine
RoHS Exemptions 6a-I / 6c	*none*
Durchgangswiderstand	< 20 mΩ
Contact Resistance	*< 20 mΩ*
Isolationswiderstand	> 1000 MΩ
Insulation Resistance	*> 1000 MΩ*
Spannungsfestigkeit	500 V AC
Withstanding Voltage	*500 V AC*
Nennspannung	250 V AC
Voltage Rating	*250 V AC*
Nennstrom	3 A
Current Rating	*3 A*
Temperaturbereich	-40 °C ... +105 °C
Temperature Range	*-40 °C ... +105 °C*
Verarbeitung	Wellen- oder Reflow-Lötverfahren
Processing	*Wave or reflow soldering*

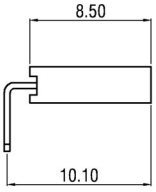


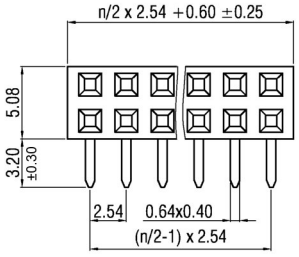
Gabelkontakte für Vierkantstifte 0,635mm.
Fork contacts accept 0.635mm square pins.

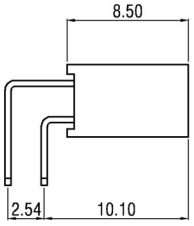












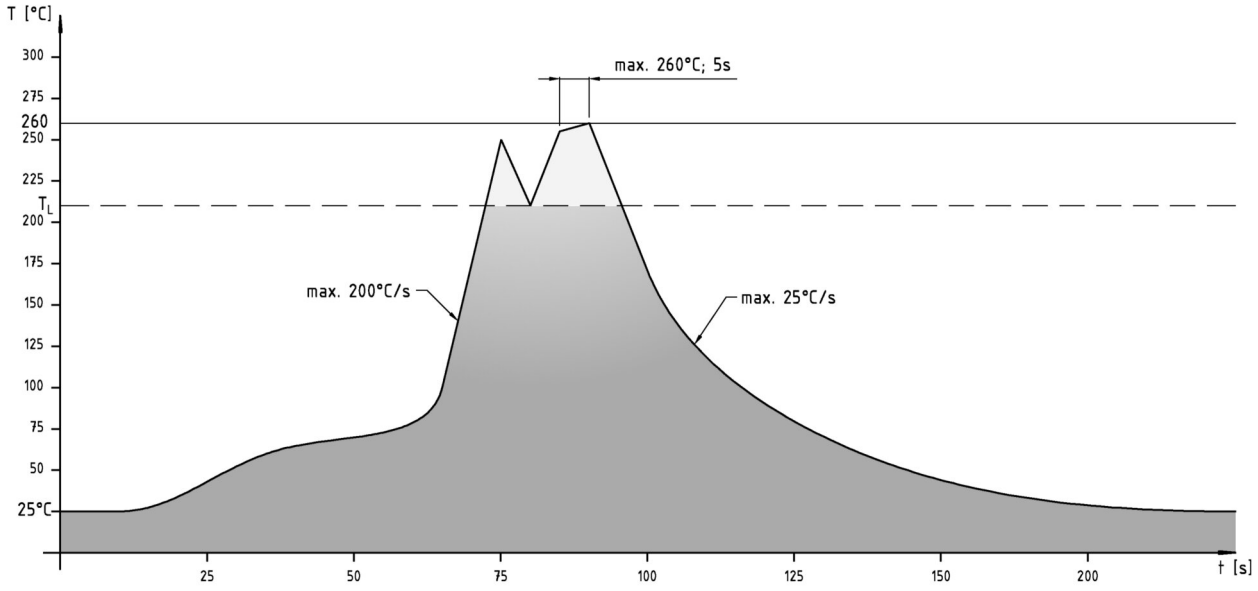
Series	***Contacts****	***Rows****	***Plating****
159	**36**	**2**	**00**
	02-36 Einreihig *Single row* **04-72** Zweireihig *Double row*	**1** Einreihig *Single row* **2** Zweireihig *Double row*	**00** Vergoldet *Gold plated* **50** Verzinnt *Tin plated* **60** Sel. Au/Sn *Duplex plating*

* Dies ist ein **Bestellbeispiel** -
bitte durch Ihre Spezifikationen ersetzen.
** This is an **order example** -*
please replace by your specifications.

Empfehlungen für das Wellenlötverfahren

Recommendations for Wave Soldering

Die Bauteile sollten bei einer Lötbadtemperatur von 260°C in max. 5 Sekunden verlötet werden.
Empfohlenes Wellenlötprofil:

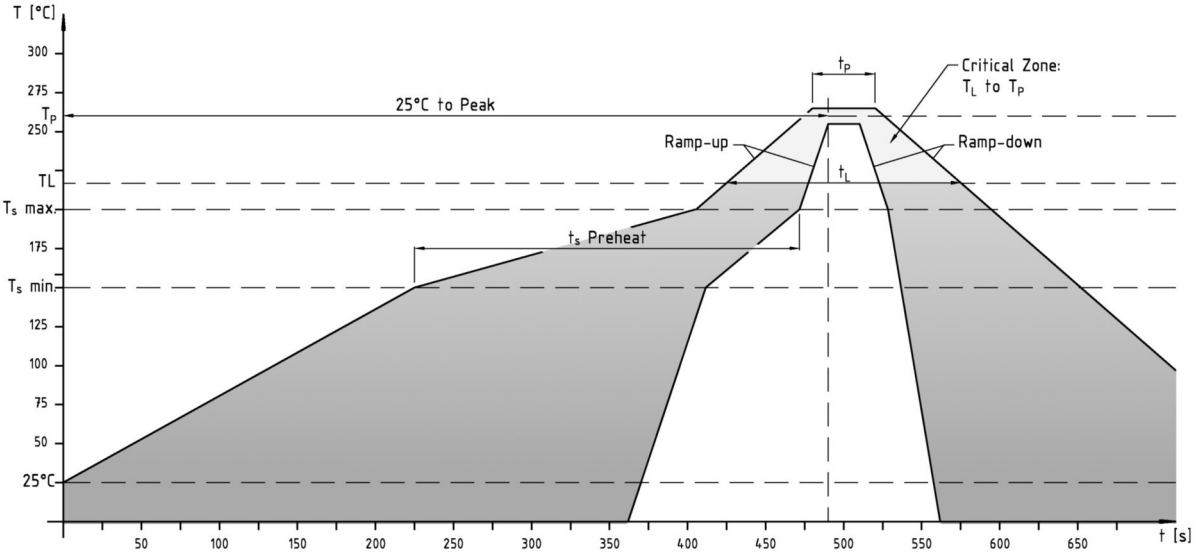


Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum $T_S$min	150 °C
Temperatur Maximum $T_S$max	200 °C
Dauer $T_S$min – $T_S$max	60 – 180s
Temperatur Lötbereich T_L	217 °C
Verweildauer oberhalb T_L	60 – 180s
Ramp-Up Rate $T_S$max – T_P	max. 3 °C / s
Höchsttemperatur T_P	260±5 °C
Dauer Höchsttemperatur	20 – 40s
Ramp-Down Rate $T_P$max – $T_S$min	6 °C / s
Dauer 25 °C – Höchsttemperatur T_P	max. 8m

Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature $T_S$min	*150 °C*
Maximum Temperatur $T_S$max	*200 °C*
Duration $T_S$min – $T_S$max	*60 – 180s*
Soldering Range Temperature T_L	*217 °C*
Duration above T_L	*60 – 180s*
Ramp-Up Rate $T_S$max – T_P	*max. 3 °C / s*
Peak Temperature T_P	*260±5 °C*
Duration Peak Temperature	*20 – 40s*
Ramp-Down Rate $T_P$max – $T_S$min	*6 °C / s*
Duration 25°C - Peak Temp. T_P	*max. 8min*